

Performance and Reliability Gains in UHV SiC Using Advanced Power Devices and Packaging Technologies

*Sascha Dern, Vice President Sales, EMEA & India
Navitas Semiconductor
December 2, 2025*

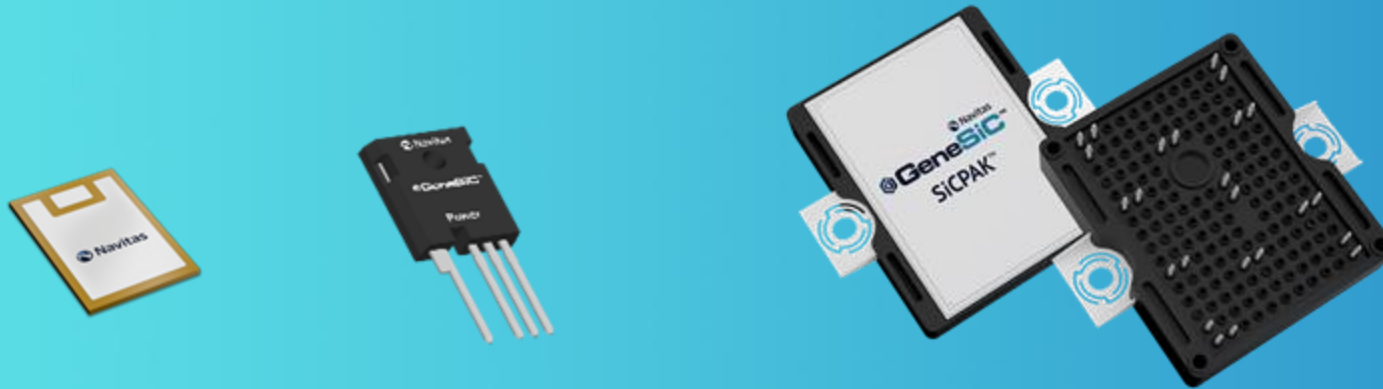
**Bodo's
Wide Bandgap
Event 2025**

Making WBG Designs Happen

SiC



Performance and Reliability Gains in UHV SiC Using Advanced Power Devices and Packaging Technologies



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Electrify Our World™

Navitas 2.0: Positioned for UHV Markets

2014

Founded



**Only
GaN + SiC**
Pure-play WBG



>300

Mpcs
shipped



700%

growth &
Deloitte Fast
500 (3 yrs)



+300

Patents issued
or pending



\$250M

Cash held with
no debt



Focus Markets



AI Data Center



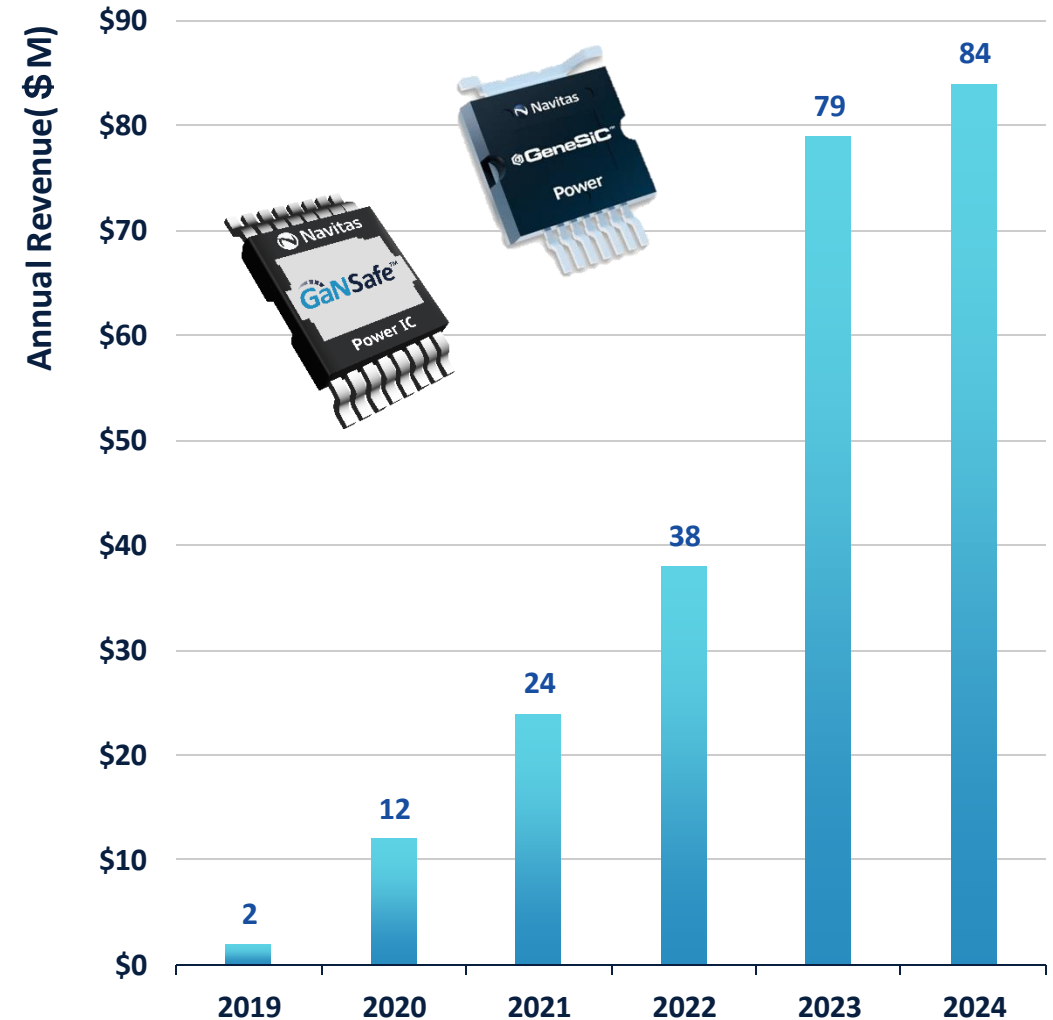
Performance
Computing



Energy and Grid
Infrastructure



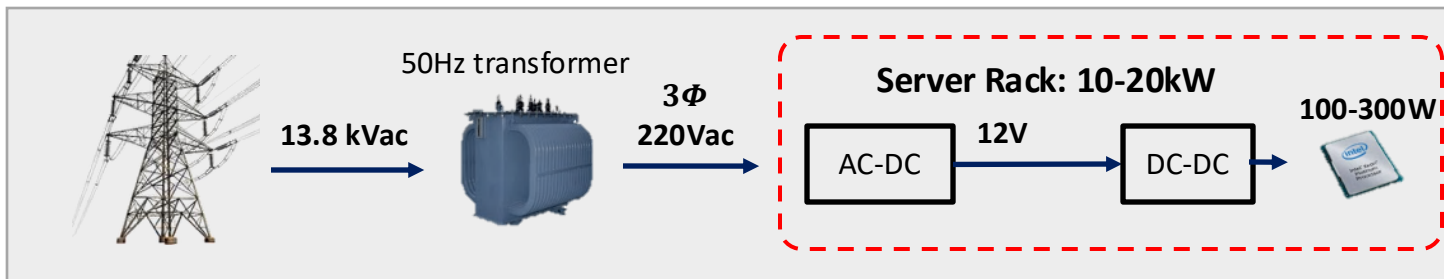
Industrial
electrification



- **Significant upgrades are underway in Energy, SST, Data Centers**
- **Wide Band Gap Power Semiconductors are critical to delivering:**
 - Higher Voltages → 1.7kV +
 - Higher Power → 1MW +
 - Greater Efficiency → 90% +
 - Longer Reliability → 20 years +
 - Scalability → Reduced material and system costs
- **Achieving these goals requires advanced Power Devices and Packaging**

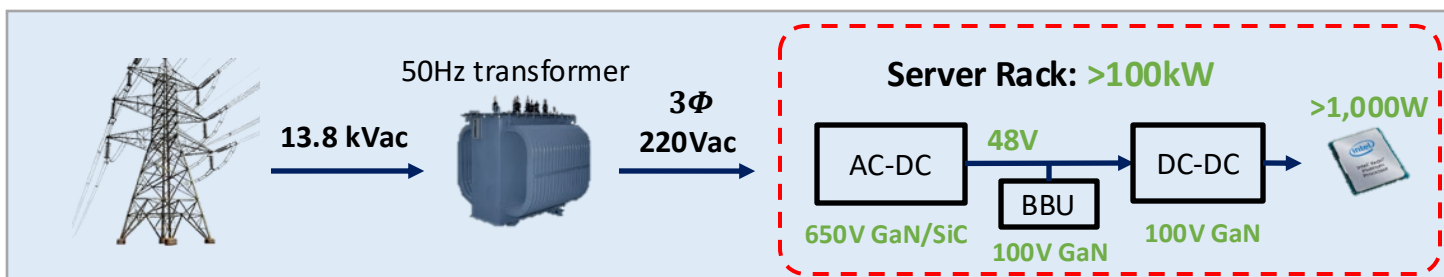
Example: Grid Efficiency Driving UHV SST

Traditional 12V Data Centers



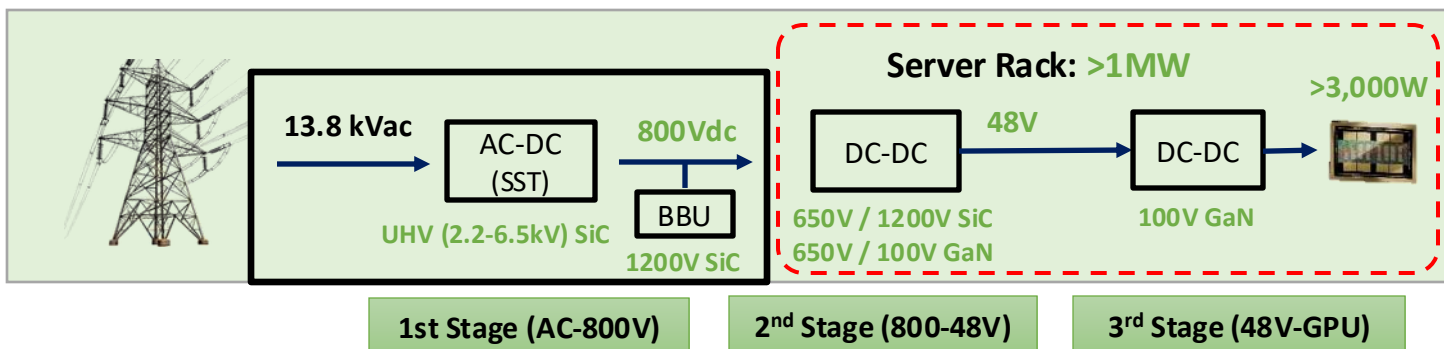
- 70-80% total energy efficiency
- 100% Si-based power systems
- Limited GaN or SiC use today

Today's AI 48V Data Centers



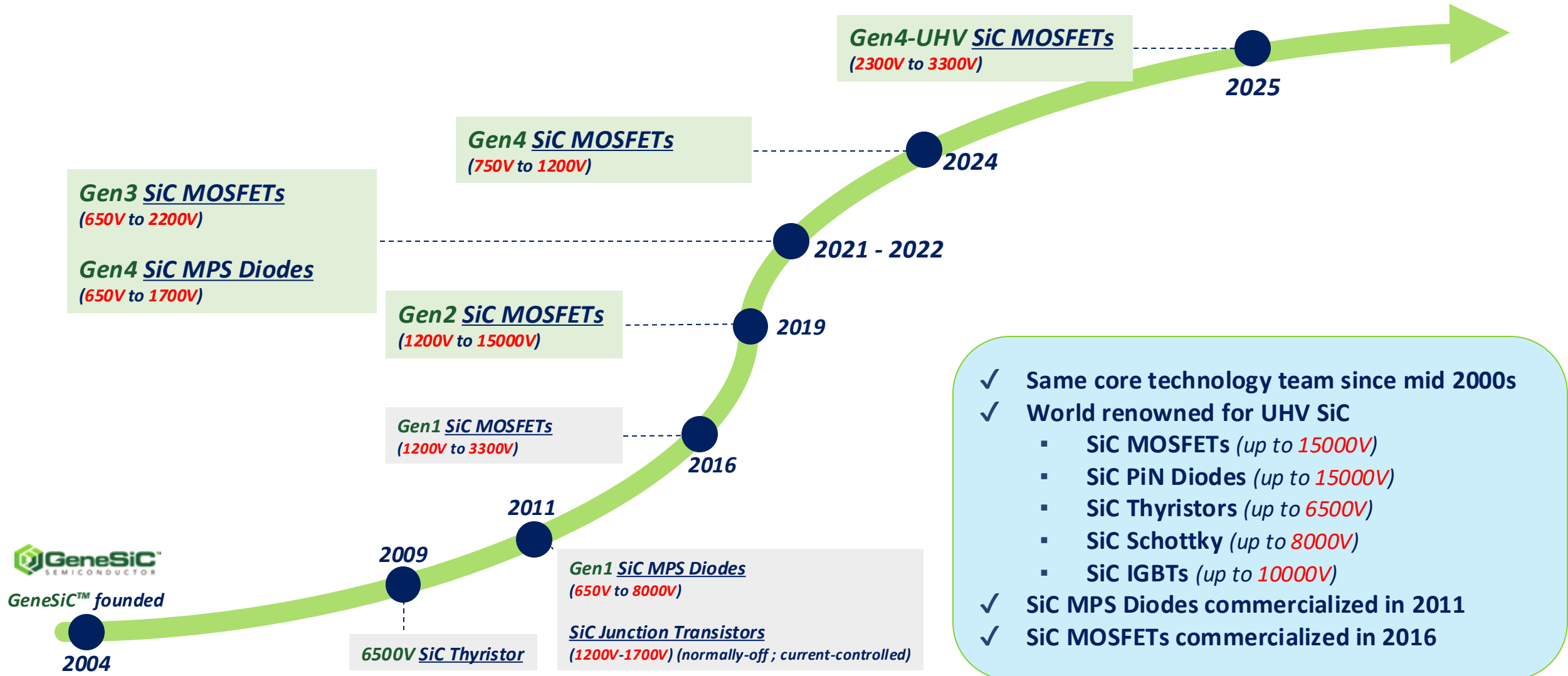
- 80-90% total energy efficiency
- Significant GaN / SiC use
- 2030 Requirements: \$1.4B/yr

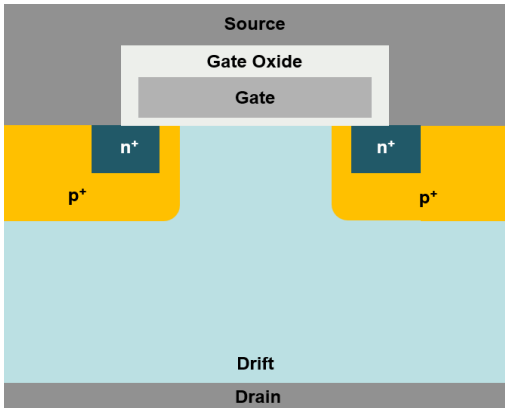
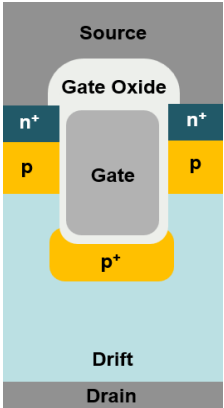
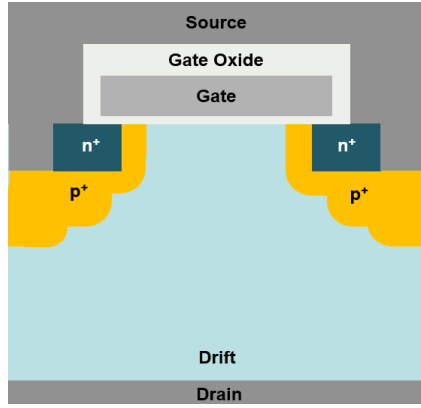
Future AI 800V Data Centers



- Target over 90% total energy efficiency
- Accelerating GaN / SiC use
- 2030 Requirements: \$2.6B/yr

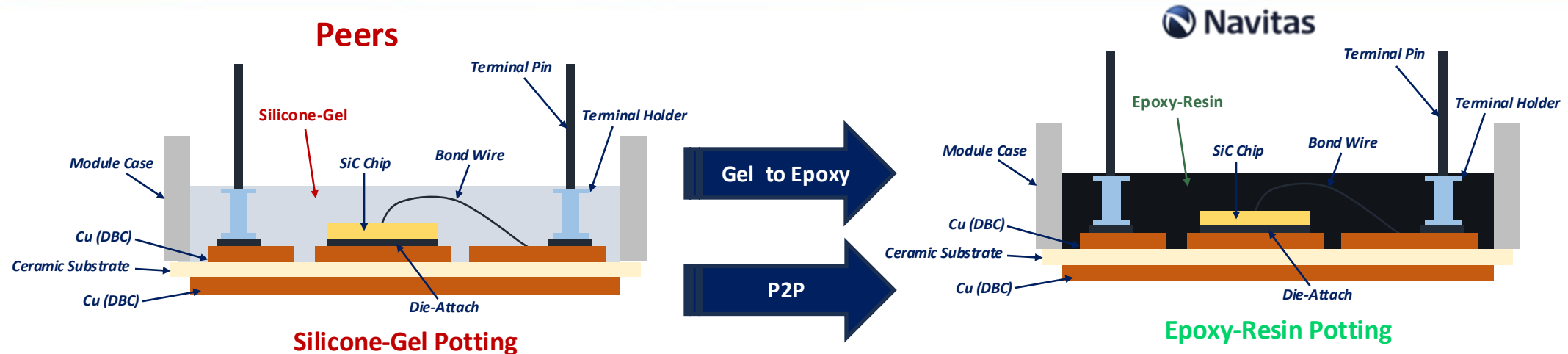
SST Accelerating Demand for UHV Power Semi



	<i>Traditional Planar</i>	<i>Standard Trench</i>	<i>Trench-Assisted Planar</i>
			
<i>Manufacturability</i>	<ul style="list-style-type: none"> ✓ Repeatable ✓ High yield ✓ Low cost 	<ul style="list-style-type: none"> – Inconsistent trench etch – Lower Yields – High Cost 	<ul style="list-style-type: none"> ✓ Repeatable ✓ High yield ✓ Low cost
<i>Performance</i>	<ul style="list-style-type: none"> – High $R_{DS(on)}/\text{area}$ – Slow Switching 	<ul style="list-style-type: none"> ✓ Lower $R_{DS(on)}/\text{area}$ ✓ Faster Switching 	<ul style="list-style-type: none"> ✓ Lower $R_{DS(on)}/\text{area}$ ✓ Faster Switching
	<ul style="list-style-type: none"> ✓ Low $R_{DS(on)}/\Delta\text{temperature}$ 	<ul style="list-style-type: none"> – High $R_{DS(on)}/\Delta\text{temperature}$ 	<ul style="list-style-type: none"> ✓ Lowest $R_{DS(on)}/\Delta\text{temperature}$
<i>Reliability</i>	<ul style="list-style-type: none"> ✓ Rugged gate oxide (stable V_{TH}) 	<ul style="list-style-type: none"> – Failures due to non-uniform gate oxide – Lower short-circuit capability 	<ul style="list-style-type: none"> ✓ Highest 100% tested avalanche ✓ Long short-circuit withstand time ✓ Rugged gate oxide (stable V_{TH})

Trench-gate advantage does not extend to SiC

Epoxy Fill for Dramatically Improved Reliability



Reliability Improvements	Navitas SiCPAK™ Qualification	Competitor Qualification
Temperature Cycling (-55°C to 150°C)	>1000 cycles	<100 cycles
Thermal Shock Test (-40°C to 125°C)*	>1000 cycles	<100 cycles
Temperature Humidity Bias (THB / HV-H3TRB)	1000 hrs 80% V_{DS} THB at module-level 1000 hrs 80% V_{DS} HV-H3TRB die-level	1000 hrs 80% V_{DS} die-level only

***After 1000 cycles of Thermal Shock Testing**

Up to 15% thermal resistance increase for epoxy-resin vs. **33%-80% increase** for silicone-gel
All epoxy-resin potted modules passed isolation tests; all silicone-gel modules failed

Thermal Shock Testing (-40°C to 125°C)

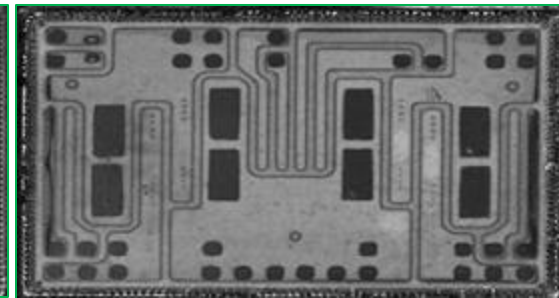
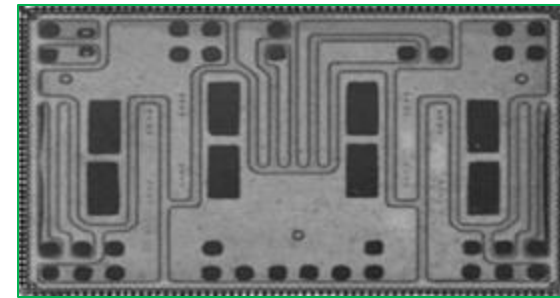
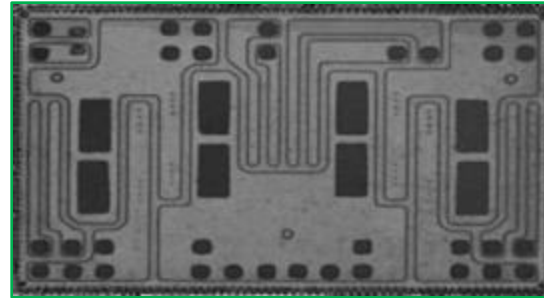
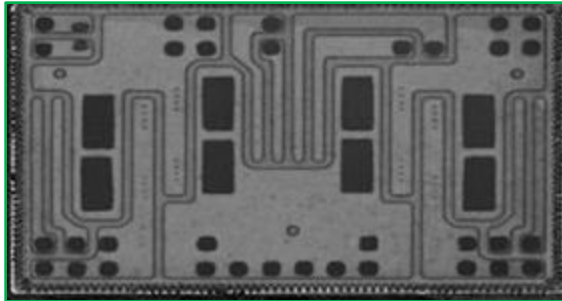
T0

100 Cycles

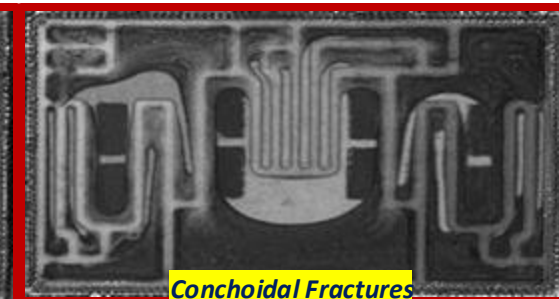
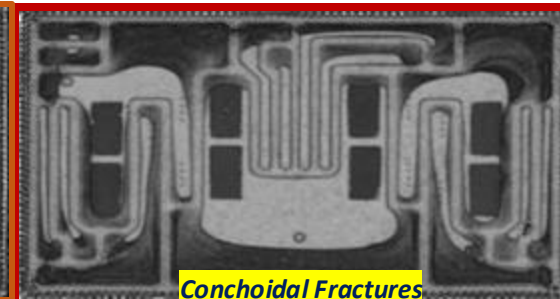
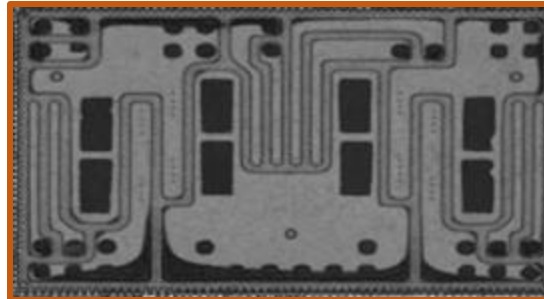
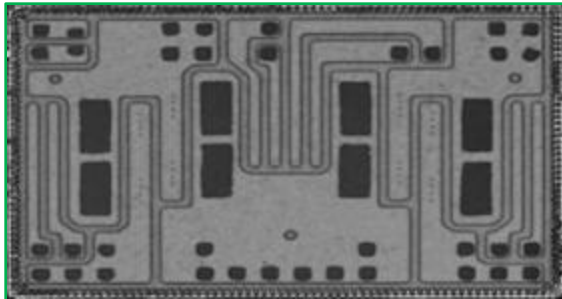
500 Cycles

1000 Cycles

Epoxy-
Resin



Silicone-
Gel



Results after 1000 cycles of Thermal Shock Testing

- ✓ Up to 15% thermal resistance increase for epoxy-resin vs. **33%-80% R_{th} increase** for silicone-gel
- ✓ All epoxy-resin potted modules passed isolation tests; **all silicone-gel modules failed isolation test**



Thank you!

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